Lam Research Corporation Ships 3,000th Single-Wafer Spin Clean Process Module

FREMONT, Calif., Apr 19, 2010 (BUSINESS WIRE) -- Lam Research Corporation (NASDAQ:LRCX), a major supplier of semiconductor wafer fabrication equipment and services, today announced it has shipped the 3,000th single-wafer SEZ(R) spin clean technology process module to a leading DRAM manufacturer. This DV-Prime(TM) wet clean system will be used for multiple applications, including cleaning high-aspect-ratio structures (up to 40:1). The system was selected for its multi-chemistry flexibility and advanced capabilities, including new drying technology that minimizes collapse of fragile features. Shipment of this 3,000th spin clean module continues Lam's leadership in maintaining the largest installed base of single-wafer wet clean modules.

"We are extremely proud of the continued success of our spin clean products as highlighted by this 3,000th shipment," said Jeff Marks, vice president and general manager, Clean Product Group, Lam Research. "This milestone shipment demonstrates customer confidence in the advanced capability delivered by recent innovations in our spin clean design."

First introduced over 20 years ago, Lam's single-wafer SEZ spin clean technology pioneered the industry transition from batch to single-wafer wet processing and is widely used in back-end-of-the-line applications. With recent design advances - including improved particle removal efficiency, new drying technology, and higher throughput - spin technology is now being used by customers for several critical front-end-of-the-line (FEOL) applications. These include gate module cleans, pre-cleans, photoresist strip, and silicide cleans, where the numerous materials involved require significant process and chemistry flexibility.

"All of our recently shipped FEOL spin clean modules are configured with multiple chemistries," added Marks, "and customers are reporting that we provide greater flexibility in chemical management on our spin clean platforms than our competitors."

Lam's spin technology is used in a broad range of applications, including particle, polymer, and residue removal; substrate thinning; photoresist removal; and backside and bevel cleaning. It is also well-suited for several critical FEOL and middle-of-the-line applications, where new capabilities deliver advanced performance specifications, increased productivity, and a lower cost of ownership. Together, the Company's spin wet clean, linear wet clean, and plasma bevel clean products provide a diverse single-wafer clean product portfolio that addresses a wide range of current and future wafer cleaning challenges.

Statements made in this press release which are not statements of historical fact are forward-looking statements and are subject to the safe harbor provisions created by the Private Securities Litigation Reform Act of 1995. Such forward-looking statements relate, but are not limited, to the customer's actual and intended use for the spin clean tools, and the actual performance and capabilities of all the tools offered by Lam. These forward-looking statements are based on current expectations and are subject to uncertainties and changes in condition, significance, value and effect as well as other risks detailed in documents filed with the Securities and Exchange Commission, including specifically the report on Form 10-K for the year ended June 28, 2009, and Form 10-Q for the quarter ended December 27, 2009, which could cause actual results to vary from expectations. The Company undertakes no obligation to update the information or statements made in this press release.

Editor Background:

Lam Research Corporation is a major supplier of wafer fabrication equipment and services to the world's semiconductor industry, where the Company has been advancing semiconductor manufacturing for 30 years. As a technology and market share leader in plasma etch and single-wafer clean, Lam Research is leveraging its combined expertise to address some of today's most advanced semiconductor processing challenges, providing customers with an expanded product portfolio. Headquartered in Fremont, California, Lam Research maintains a global network of service facilities throughout North America, Asia, and Europe to meet the complex and changing needs of its global customer base. Lam's common stock trades on The NASDAQ Global Select Market(SM) under the symbol LRCX. Lam Research is a NASDAQ-100(R) company. For more information, visit http://www.lamresearch.com.

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